

What is claimed is:

1. An IC socket comprising:

a multitude of elastic contact pins arranged to form an array;  
a socket body by which respective lower end sections of said contact pins are movably supported;

5 a floating member which is vertically movably held above said socket body and by which respective upper end sections of said contact pins are movably supported; and

a cover member constructed to be fitted to said floating member so as to press said floating member toward said socket body,

10 wherein said floating member is provided with: a multitude of guide means for regulating amount of projection of the upper end sections of said contact pins from said floating member; and a container section for containing an IC package to bring a multitude of terminals of the IC package into contact with the upper end sections of said multitude of contact pins, respectively, and

15 wherein where said cover member is fitted to said floating member and pressed down upon the IC package being put in said container section, contact at predetermined pressure is obtained between the lower end sections of said contact pins and electrodes of a printed circuit board and between the upper end sections of said contact pins and the terminals of the IC package, respectively.

2. An IC socket comprising:

a multitude of elastic contact pins arranged to form an array;

a socket body by which respective lower end sections of said contact pins are fixedly supported as projecting downward therefrom;

5 a floating member which is vertically movably held above said socket body and by which respective upper end sections of said contact pins are movably supported; and

a cover member constructed to be fitted to said floating member so as to press said floating member toward said socket body,

10 wherein said floating member is provided with: a multitude of guide means for regulating amount of projection of the upper end sections of said contact pins from said floating member; and a container section for containing an IC package to bring a multitude of terminals of the IC package into contact with the upper end sections 15 of said multitude of contact pins, respectively, and

wherein where said cover member is fitted to said floating member and pressed down upon the IC package being put in said container section, contact at predetermined pressure is obtained between the upper end sections of said contact pins and the terminals 20 of the IC package.

3. An IC socket according to claim 2, wherein the terminals of the IC package are constructed to be ball terminals and an inclined face is formed at a tip of the upper end section of each contact pin so as to be contacted with and rubbed against a portion, exclusive of 5 a bottom point, of each ball terminal.

4. An IC socket according to claims 1 or 2, wherein said

5        container section forms an aperture in said floating member, and said cover member has a first surface to be contacted with a top surface of said floating member and a second surface to be contacted with an upper surface of the IC package which is contained in said container section, said IC socket being constructed such that said second surface is brought into contact with the upper surface of the IC package contained in said container section before said first surface is brought into contact with said top surface of said floating member 10        in a process of said cover member being fitted in place.

5.        An IC socket according to claims 1 or 2, wherein the terminals of the IC package are constructed to be solder balls, and said guide means of said floating member are arranged such that the upper end sections of said contact pins are directed toward respective centers 5        of the solder balls.

6.        An IC socket according to claims 1 or 2, wherein the tip of the upper end section of each contact pin has at least one face which is inclined in reference to a longitudinal direction of said contact pin.

7.        An IC socket according to claims 1 or 2, wherein each of said contact pins has an arc-shaped middle section between the upper end section and the lower end section, said contact pin being cornered at points where the upper end section and the lower end section meet the 5        middle section, respectively, such that the upper end section and the

lower end section are aligned.

8. An IC socket according to claims 1 or 2, wherein each of said contact pins has a step portion which is formed at a position lower than the tip of the upper end section of said contact pin by a predetermined distance.

9. An IC socket according to claims 1 or 2, wherein each of said guide means of said floating member forms a guide hole which is slightly tapered from a lower border to an upper border thereof.

10. An IC socket according to claim 9, wherein the lower border of said guide hole has a curved face.